

ABSTRACT

CONVEYING APPARATUS

A conveying apparatus is provided. The conveying apparatus including: a holding plate having a holding surface destined to face a surface to be held of a wafer; a restriction member provided on one end side of the holding surface, the restriction member adapted to contact a peripheral surface of the wafer so as to restrict movement of the wafer toward the one end side; and a moving unit adapted to move the holding plate. At the holding surface, there is formed a non-contact type suction holding part which is adapted to jet a fluid obliquely to the surface to be held of the wafer so as to move the wafer in a direction toward the restriction member and to generate a negative pressure between the holding surface and the surface to be held, thereby holding the wafer by suction. The fluid is jetted from the suction holding part so as to abut the wafer against the restriction member, thereby positioning the wafer at a predetermined position on the holding plate.

(Figure 2)